L Number	Hits	Search Text REST AV. OPY	DB	Time stamp
1	14	6,124,641	USPAT;	2003/10/27 16:48
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
2	668	MSQ (methyl adj silsesquioxane)	USPAT;	2003/10/27 16:49
			US-PGPUB;	
			EPO; JPO;	- 8
			DERWENT;	
			IBM_TDB	
3	55327	(cure cured curing cures) near12 \$4degree	USPAT;	2003/10/27 16:51
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	400		IBM_TDB	0000410407.40.54
4	103	(MSQ (methyl adj silsesquioxane)) and ((cure cured curing	USPAT;	2003/10/27 16:51
		cures) near12 \$4degree)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	1-	(MCC (mothed adiable annihology and (forms are de-	IBM_TDB	0000/40/07 47:40
5	15	((MSQ (methyl adj silsesquioxane)) and ((cure cured curing	USPAT;	2003/10/27 17:12
		cures) near12 \$4degree)) and ((carbon C) near3 (percent	US-PGPUB;	
		percentage "%" or "at%" or "wt%"))	EPO; JPO;	
			DERWENT;	
	•	(#5504704# 1 #5044550# 1 #5000000# 1 #0074007# 1 #0444050# 1	IBM_TDB	0000/40/07 40:50
6	9	("5534731" "5641559" "5989998" "6071807" "6114259"	USPAT	2003/10/27 16:59
7	27	"6127258" "6232235" "6303047" "6331494").PN.	LICDAT	2002/40/27 47:00
7	27	5534731.URPN.	USPAT	2003/10/27 17:08
8	32	organic adj spin adj (glass dielectric insulat\$3)	USPAT;	2003/10/27 17:11
			US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM_TDB	
9	610	organic adj SOG	USPAT;	2003/10/27 17:12
•	010		US-PGPUB;	2003/10/27 17.12
			EPO; JPO;	
1			DERWENT;	
			IBM_TDB	
10	623	organic adj spin adj (glass dielectric insulat\$3)) (organic adj	USPAT;	2003/10/27 17:12
'	020	SOG)	US-PGPUB;	2000/10/2/ 17:12
		(000)	EPO; JPO;	
<u> </u>			DERWENT;	
			IBM_TDB	
12	7	(((cure cured curing cures) near12 \$4degree) and ((organic	USPAT;	2003/10/27 17:12
	ĺ,	adj spin adj (glass dielectric insulat\$3)) (organic adj SOG)))	US-PGPUB;	
		and ((carbon C) near3 (percent percentage "%" or "at%" or	EPO; JPO;	
		"wt%"))	DERWENT:	
		"	IBM_TDB	
11	97	((cure cured curing cures) near12 \$4degree) and ((organic	USPAT;	2003/10/27 17:49
		adj spin adj (glass dielectric insulat\$3)) (organic adj SOG))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
13	6	dow.in. and (low adj2 (dielectric k))	USPAT;	2003/10/27 17:52
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
14	53	dow.in. and dielectric	USPAT;	2003/10/27 17:51
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	

15	228	dow.asn. and (low adj2 (dielectric k))	USPAT;	2003/10/27 17:52
			US-PGPUB; EPO; JPO; DERWENT;	
16	145	(dow.asn. and (low adj2 (dielectric k))) and organic	IBM_TDB USPAT; US-PGPUB;	2003/10/27 17:52
			EPO; JPO; DERWENT; IBM_TDB	

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